

Plasma Cleaner/Plasma Asher PC03/PC04/PA03B

low pressure plasma cleaner system can modify all kinds of printing or adhesive substrates prior to surface activation, modification, grafting, roughening or cleaning.

Product Features

- Extremely high plasma uniformity
- No substrate damage due to the use of low energy ions
- No contamination of substrates due to high energy bombardments of electrodes
- Special plasma electrode design
- High density plasma source
 - High plasma performance
 - Well-controlled low ion energy
 - Combination of chemical reactivity and physical bombardments
- High cleaning efficiency
- Wide operation condition
- Multiple processing gases capable of achieving the best surface cleaning and treatment effects
- Fully automatic and user-friendly
- High reliability and easy maintenance
- Customization



| Specifications | PC03 / PC04 | PA03B |
|-------------------------|---|---|
| Applications | <ul style="list-style-type: none"> ■ LCM, IC Packaging (Flip Chip, CSP, BGA, Lead Frame, etc.), LED packaging, SMT, PCB, FPC, optoelectronic components, electronic components, Packaging before the clean. ■ Before printing or adhesive surface roughening or cleaning. | <ul style="list-style-type: none"> ■ Removal of residual photoresist ■ Blue film residue removal ■ Incoming PSS cleaning process |
| Footprint | 1270(W)×1100(D)×2216(H)mm | |
| Chamber Size | 500(W)×500(D)×500(H)mm | |
| Weight | 880kg | |
| Facilities | 3Ø220V×60Hz×4w·30A Compressed air : ~6 kg/cm ² Reaction gas : ~3 kg/cm ² | 3Ø220V×60Hz×4w·50A Compressed air : ~6 kg/cm ² Reaction gas : ~3 kg/cm ² |
| System Control Software | PC or PLC | |
| Gas Flow System | 2 mass flow controllers | 1 mass flow controllers |
| Vacuum Pump | Rotary (80m ³ /hr) + Roots(250m ³ /hr) | Rotary pump |
| Reactants | O ₂ , Ar, H ₂ , N ₂ & mixing gases | O ₂ ,N ₂ ,H ₂ ,CF ₄ ,&mixing gases |

